Chip Specification Brief Overview

CECS 460

What is a Chip Specification?

- Design team creates the "official document" for the SOC/Chip design
- It contains all of the information that one would need to know in order to include the SOC/Chip into a design
- The information needs to address several areas:
 - The physical characteristics (package type, pin count, pin out, current requirements, etc.)
 - The hardware implementation (what does the chip contain, what can one do with it, etc.)
 - The software interface (how does one program the device, what are the register addresses/contents)

Chip Specification in 460

- The goal of 460 is to produce an SOC (chip design)
- We write our own IP (AISO, UART, etc.)
- We instantiate commercially available IP (PicoBlaze)
- We interface to external devices (memory)
- The Chip Spec is the final deliverable for your work this semester and should be prepared with care
- It should document the design through the work you have accomplished.

Examples

- For the LPC2148 the chip specification is the UM10139 document (the more functionality contained within a device the more information needs to be included in the specification)
- For the Spartan-3E FPGA there is the Spartan-3 Generation FPGA User Guide
- Every device meant for public consumption must have a well written chip specification. This will enable the users to quickly integrate the device into their own designs with as little confusion as possible

Our Class

- I worked for a company, Valence Semiconductors (now defunct), that needed a clear methodology documented for the engineering organization
- We produced a Chip Specification Template that has been placed in the lectures folder on BeachBoard.
 - This is for reference only there is way too much information required that we will not need to document
 - The next page will outline the contents of our chip spec that will be expected to be included



Chip Specification Template

Verilog Source Code

- The chip specification should thoroughly define the design of the chip as a written document
- The reader should understand what are the components of the design and what the purpose of each is
- The Verilog is for reference and should be included as an organized appendix
- The assembly code is also for reference and should also be included as an organized appendix
- The assembly code should be thoroughly described under the banner of "software"

Chip Spec Outline

- Introduction
- II. Documents
 - A. Applicable External Documents
 - B. Applicable Internal Documents
- III. Requirements
- IV. Top Level Design
 - A. Description
 - B. Block Diagram
 - C. Data Flow Description
 - D. I/O
 - 1. Signal Names
 - 2. Pin Assignments
 - Electrical Characteristics
 - E. Clocks
 - F. Resets
 - G. Software
- V. Externally Developed Blocks
 - A. Description
 - B. Block Diagram
 - C. I/O
 - D. Register Map
- VI. Internally Developed Blocks
 - A. Description
 - B. Block Diagram
 - C. I/O
 - D. State Machines
 - E. Register Map
 - F. Verification
- VII. Chip Level Verification
- VIII.Chip Level Test